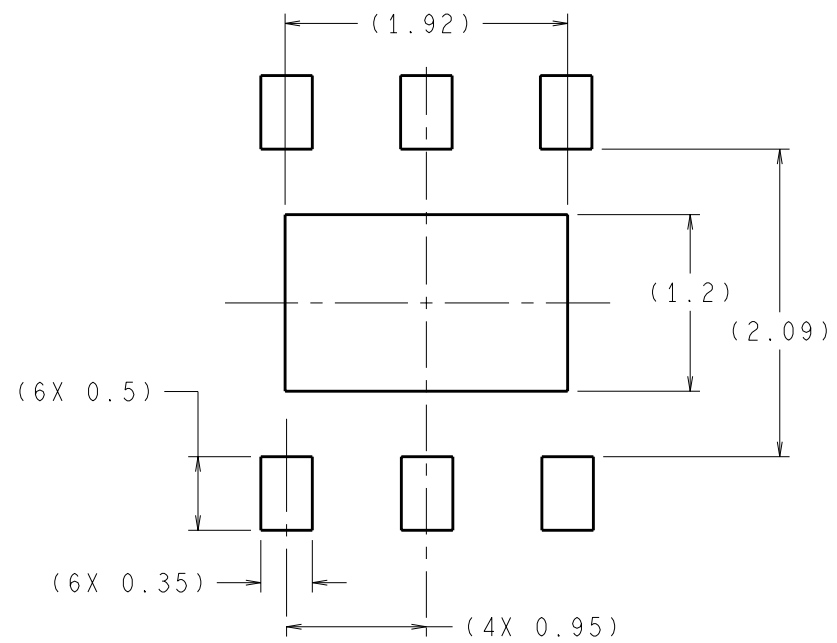
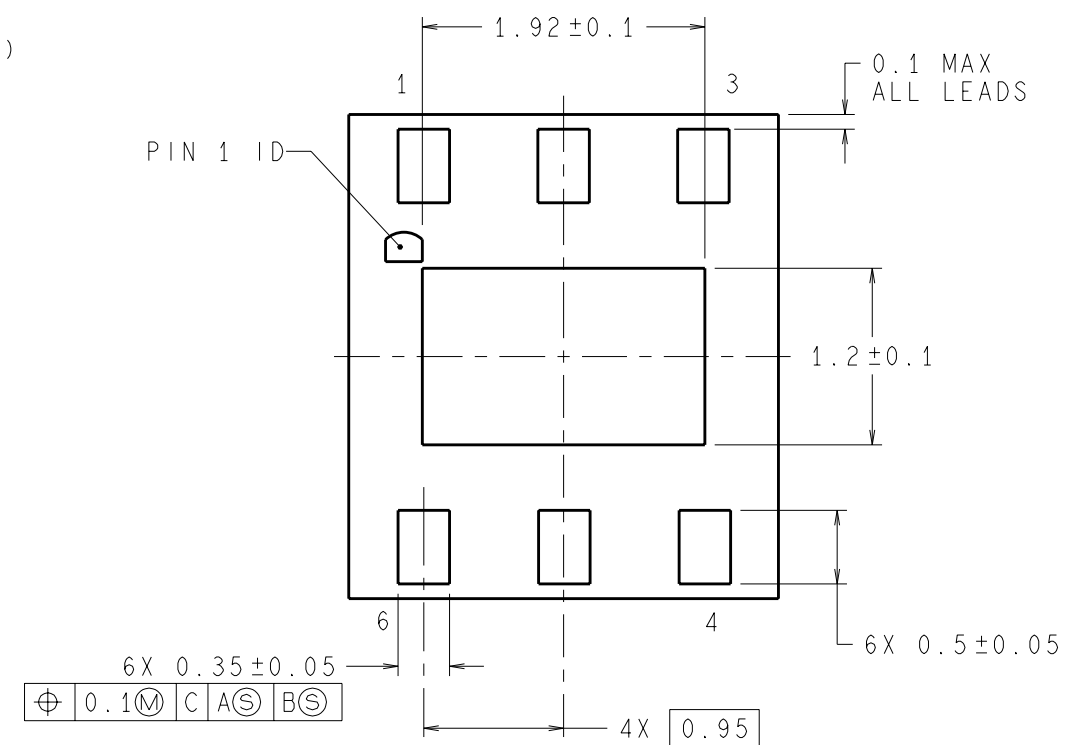
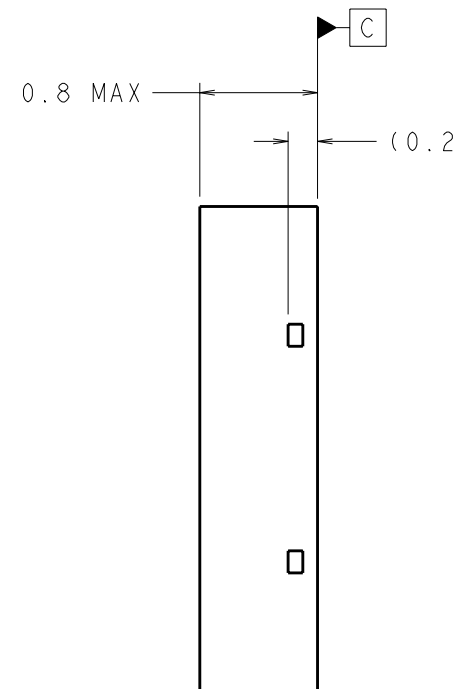
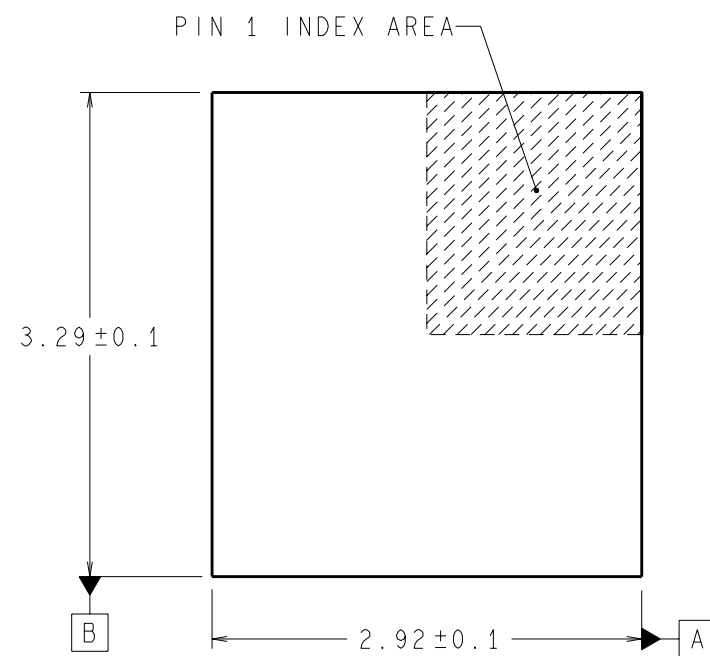


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	383	07/25/2001	SN/TL/SN



DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM LEAD/TIN (SOLDER) ON COPPER.
- NO JEDEC REGISTRATION AS OF JULY 2001.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN N. SANTHIRAN		07/25/2001			
DFTG. CHK. THANH LEQUANG		07/25/2001			
ENGR. CHK. N. SANTHIRAN		07/25/2001	LLP, PLASTIC, DUAL, 2.92 X 3.29 X 0.75 mm BODY, 6 LD, 0.95mm PITCH, SOT-23 LAND		
 PROJECTION INCH [MM]		SCALE N/A			SIZE C
FORMERLY: N/A		SHEET 1 of 1			